

SI4948BEY-T1-E3-VB Datasheet

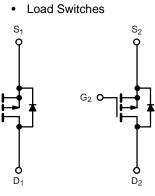
Dual P-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^{d, e}	A) ^{d, e} Q _g (Typ.)		
- 60	0.059 at V _{GS} = - 10 V	- 5.3	17 nC		
- 60	0.069 at V _{GS} = - 4.5 V	- 5.0	17 110		

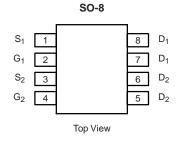
FEATURES

- Halogen-free
- TrenchFET[®] Power MOSFET
- 100 % UIS Tested

APPLICATIONS



RoHS COMPLIANT



P-Channel MOSFET

G1 0

P-Channel MOSFET

Typical

ABSOLUTE MAXIMUM RATINGS T Parameter	Symbol	Limit	Unit		
			Onic		
Drain-Source Voltage	V _{DS}	- 60	V		
Gate-Source Voltage		V _{GS}	± 20		
	T _C = 25 °C		- 5.3 ^e		
Continuous Drain Current ($T_1 = 150 \ ^{\circ}C$)	T _C = 70 °C		- 5.0 ^e		
	T _A = 25 °C	I _D	- 5.3 ^{a, b}		
	T _A = 70 °C		- 5.0 ^{a, b}	A	
Pulsed Drain Current	I _{DM}	- 32 ^e	A		
	T _C = 25 °C	1-	- 4.1		
Continuous Source-Drain Diode Current	T _A = 25 °C	Is Is	- 2.0 ^{a, b}		
Avalanche Current	L = 0.1 mH	I _{AS}	- 20		
Single-Pulse Avalanche Energy		E _{AS}	20	mJ	
	T _C = 25 °C		4.0		
Maximum Dawar Dissinction	T _C = 70 °C	P _D	2.5	w	
Maximum Power Dissipation	T _A = 25 °C	FD FD	2.0 ^{a, b}		
	T _A = 70 °C		1.4 ^{a, b}		
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS Parameter Symbol

Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	38	50	°C/W
Maximum Junction-to-Foot	Steady State	R _{thJF}	20	25	0/11

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. t = 10 s.

c. Maximum under Steady State conditions is 85 °C/W.

d. Based on T_C = 25 °C.

e. Limited by package.

Unit

Maximum

5	3	[®] VBsemi
W١	ww.\	/Bsemi.com

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static					1	1	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 60			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			- 31		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		4.5			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 1.0		- 3.0	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			- 1		
Zero Gale voltage Drain Current	USS	$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 \text{ °C}$			- 5 µA		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, \text{ V}_{GS} = -10 \text{ V}$	- 30			A	
Drain Source On State Desistence		V_{GS} = - 10 V, I _D = - 6.3 A		0.054		Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 6.2 A		0.060			
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 6.1 A		23		S	
Dynamic ^b							
Input Capacitance	C _{iss}			1345			
Output Capacitance	C _{oss}	V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz		210		pF	
Reverse Transfer Capacitance	C _{rss}			180			
Total Cata Charge	Q _g	$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -6.1 \text{ A}$		32	50	nC	
Total Gate Charge				15	25		
Gate-Source Charge	Q _{gs}	$V_{DS} = -15 V, V_{GS} = -4.5 V, I_{D} = -6.1 A$		4			
Gate-Drain Charge	Q _{gd}			7.5			
Gate Resistance	R _g	f = 1 MHz		5.8		Ω	
Turn-On Delay Time	t _{d(on)}			10	15		
Rise Time	t _r	V_{DD} = - 15 V, R_L = 15 Ω		8	15		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 1 A, V_{GEN} = - 10 V, R_g = 1 Ω		45	70		
Fall Time	t _f			12	25	ns	
Turn-On Delay Time	t _{d(on)}			42	70	115	
Rise Time	t _r	V_{DD} = - 15 V, R_L = 15 Ω		35	60		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 1 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		40	70		
Fall Time	t _f			16	30		
Drain-Source Body Diode Characterist	ics						
Continous Source-Drain Diode Current	۱ _S	T _C = 25 °C			- 4.1	А	
Pulse Diode Forward Current	I _{SM}				- 32	A	
Body Diode Voltage	V _{SD}	I _S = - 2 A, V _{GS} = 0 V		- 0.75	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			34	60	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = - 2 A, dl/dt = 100 A/µs, T _{.I} = 25 °C		22	40	nC	
Reverse Recovery Fall Time	t _a	$F = 2 A, u/u = 100 A/\mu s, T_{J} = 25 C$		11		D C	
Reverse Recovery Rise Time	t _b			23		ns	

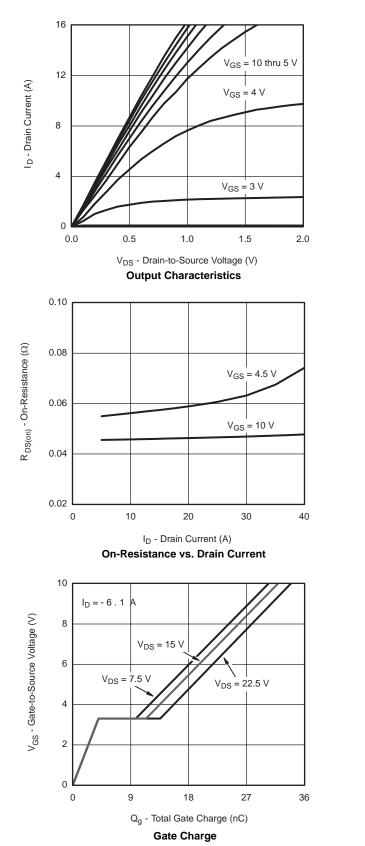
Notes:

a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

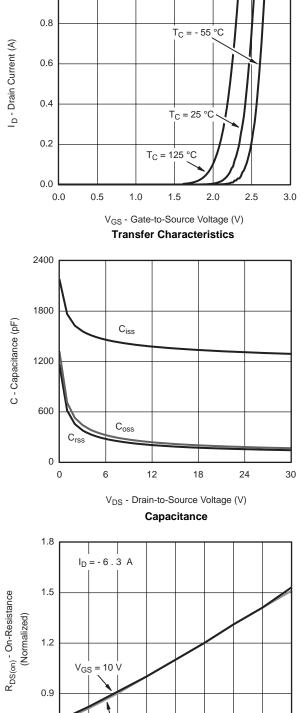
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





TYPICAL CHARACTERISTICS 25 C, unless otherwise noted



V_{GS} = 4.5 V

25

50

T_J - Junction Temperature (°C) On-Resistance vs. Junction Temperature

75

100

125 150

0

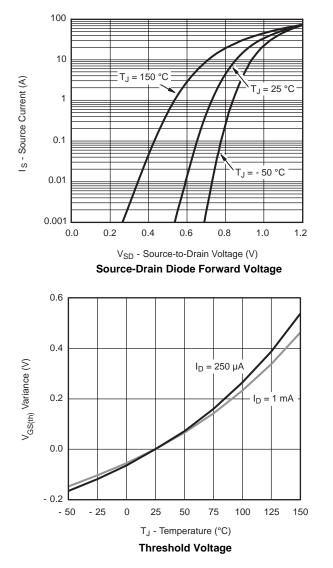
0.6

- 50

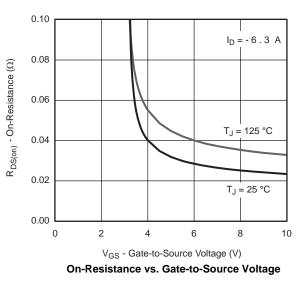
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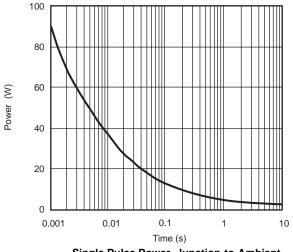
1.0



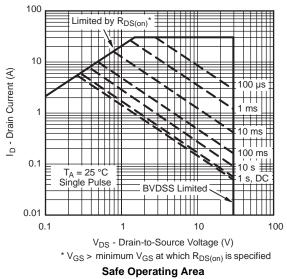


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



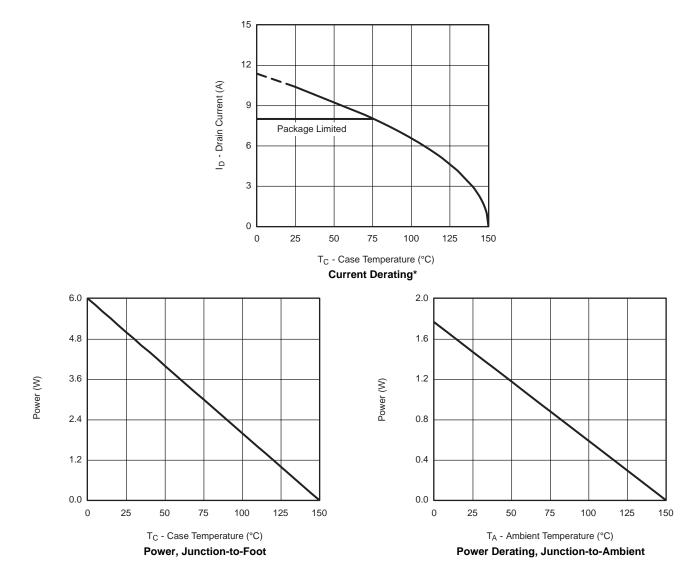


Single Pulse Power, Junction-to-Ambient





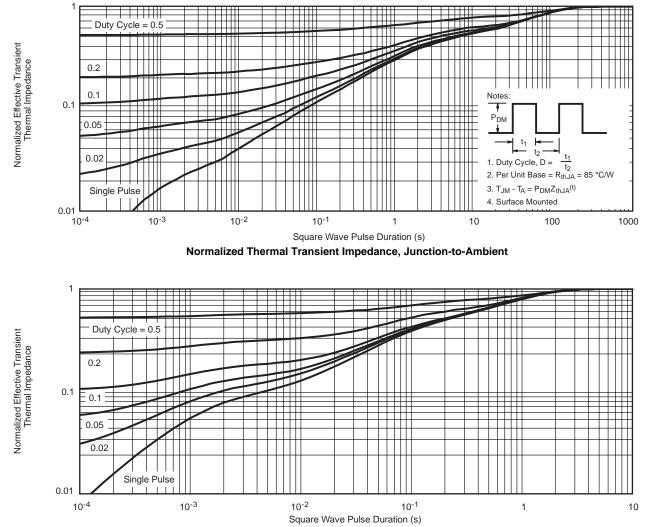
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEAD

JEDEC Part Number: MS-012

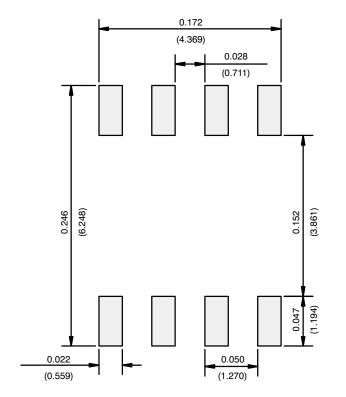




	MILLIM	IETERS	INC	HES	
DIM	Min	Мах	Min	Max	
A	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498					



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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